

Texas Instruments

Reliability Estimator

	MTBF / FIT		MTBF / FIT supporting data							
Part number	MTBF	FIT	Usage temp (°C)	Conf level (%)	Activation energy (eV)	Test temp (°C)	Test duration (hours)	Sample size	Fails	Additional comments
ADS8355IRTER	5.61×10^9	0.2	55	60.0	0.7	125	1000	65488	0	

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